



How to test bonds » external sources » semiconductor engineering

- Fraunhofer Institute for reliability and microintegration
- Interuniversity MicroElectronics Center
- MASER Engineering offers engineering support, test and diagnostics to the electronics industry
- Technical University Dresden
- International Microelectronics and Packaging Society

How to test bonds?

- Cold Bump Pull (CBP)
- Tweezer Pull (WP)
- Wire Pull (WP)

External sources

- General
- Semiconductor alliances
- Semiconductor engineering
- Process control
- Articles and papers

This information can also be found at www.qualitycontrol.how

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Other offices

- Germany
- Taiwan
- Thailand
- United Kingdom
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Bond testers

- Condor *Sigma*
- Condor *Sigma Lite*
- Condor *Sigma W12*
- Condor *150HF*

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